Yuanming Chen

List of Publications by Year
in descending order

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52 papers	888 citations	567281 15 h-index	526287 27 g-index
52 all docs	52 docs citations	52 times ranked	665 citing authors

#	Article	IF	Citations
1	Plating Uniformity of Bottom-up Copper Pillars and Patterns for IC Substrates with Additive-assisted Electrodeposition. Electrochimica Acta, 2014, 120, 293-301.	5.2	77
2	Metal oxide alternatives for efficient electron transport in perovskite solar cells: beyond TiO₂ and SnO₂. Journal of Materials Chemistry A, 2020, 8, 19768-19787.	10.3	60
3	Computational analysis and experimental evidence of two typical levelers for acid copper electroplating. Electrochimica Acta, 2018, 273, 318-326.	5.2	55
4	Labelâ€free diagnosis for colorectal cancer through coffee ringâ€assisted surfaceâ€enhanced Raman spectroscopy on blood serum. Journal of Biophotonics, 2020, 13, e201960176.	2.3	52
5	A comparison of typical additives for copper electroplating based on theoretical computation. Computational Materials Science, 2018, 147, 95-102.	3.0	49
6	Investigation of poly (1-vinyl imidazole co 1, 4-butanediol diglycidyl ether) as a leveler for copper electroplating of through-hole. Electrochimica Acta, 2018, 283, 560-567.	5.2	49
7	Optoplasmonic Hybrid Materials for Trace Detection of Methamphetamine in Biological Fluids through SERS. ACS Applied Materials & Interfaces, 2020, 12, 24192-24200.	8.0	43
8	Copolymer of Pyrrole and 1,4-Butanediol Diglycidyl as an Efficient Additive Leveler for Through-Hole Copper Electroplating. ACS Omega, 2020, 5, 4868-4874.	3.5	37
9	Compatible Ag⁺ Complex-Assisted Ultrafine Copper Pattern Deposition on Poly(ethylene) Tj ETQq1 1 0.784314 rgBT /Ov 44811-44819.	8.0	36
10	Properties and application of polyimideâ€based composites by blending surface functionalized boron nitride nanoplates. Journal of Applied Polymer Science, 2015, 132, .	2.6	28
11	Enhancing adhesion performance of sputtering Ti/Cu film on pretreated composite prepreg for stacking structure of IC substrates. Composites Part B: Engineering, 2019, 158, 400-405.	12.0	27
12	Improved Uniformity of Conformal Through-Hole Copper Electrodeposition by Revision of Plating Cell Configuration. Journal of the Electrochemical Society, 2015, 162, D575-D583.	2.9	21
13	Direct activation of copper electroplating on conductive composite of polythiophene surface-coated with nickel nanoparticles. Composites Part B: Engineering, 2018, 154, 257-262.	12.0	18
14	Solvent-dependent ultrasonic surface treatment on morphological reconstruction of CuO particles for copper electrodeposition. Applied Surface Science, 2019, 491, 206-215.	6.1	17
15	Air-plasma surface modification of epoxy resin substrate to improve electroless copper plating of printed circuit board. Vacuum, 2019, 170, 108967.	3.5	16
16	Initiation electroless nickel plating by atomic hydrogen for PCB final finishing. Chemical Engineering Journal, 2016, 306, 117-123.	12.7	15
17	Study on brown oxidation process with imidazole group, mercapto group and heterocyclic compounds in printed circuit board industry. Journal of Adhesion Science and Technology, 2015, 29, 1178-1189.	2.6	14
18	Electrochemical Factors of Levelers on Plating Uniformity of Through-Holes: Simulation and Experiments. Journal of the Electrochemical Society, 2018, 165, E359-E365.	2.9	14

#	Article	IF	Citations
19	Convection-Dependent Competitive Adsorption between SPS and EO/PO on Copper Surface for Accelerating Trench Filling. Journal of the Electrochemical Society, 2019, 166, D93-D98.	2.9	14
20	Improving wettability of photo-resistive film surface with plasma surface modification for coplanar copper pillar plating of IC substrates. Applied Surface Science, 2017, 411, 82-90.	6.1	13
21	Enhancing inductance of spiral copper inductor with BaFe 12 O 19 /poly (phenylene oxide) composite as an embedded magnetic core. Composites Part B: Engineering, 2018, 138, 232-242.	12.0	13
22	Nickel-nanoparticles-assisted direct copper-electroplating on polythiophene conductive polymers for PCB dielectric holes. Journal of the Taiwan Institute of Chemical Engineers, 2019, 100, 262-268.	5.3	13
23	Investigation of polyvinylpyrrolidone as an inhibitor for trench super-filling of cobalt electrodeposition. Journal of the Taiwan Institute of Chemical Engineers, 2020, 112, 232-239.	5.3	13
24	Temperature-dependent inhibition of PEG in acid copper plating: Theoretical analysis and experiment evidence. Materials Today Communications, 2020, 24, 100973.	1.9	13
25	Effects of surfaceâ€functionalized aluminum nitride on thermal, electrical, and mechanical behaviors of polyarylene ether nitrileâ€based composites. Polymer Composites, 2016, 37, 3033-3041.	4.6	12
26	Enhancing adhesion performance of no-flow prepreg to form multilayer structure of printed circuit boards with plasma-induced surface modification. Surface and Coatings Technology, 2018, 333, 24-31.	4.8	12
27	Electric and thermal performance of poly(phenylene oxide)â€based composites with synergetic modification of carbon nanotubes and nanoplatelets. Polymer Composites, 2018, 39, E1920.	4.6	12
28	Whisker inhibited Snâ€“Bi alloy coating on copper surface to increase copper bonding strength for signal loss reduction of PCB in high-frequency. Applied Surface Science, 2020, 513, 145718.	6.1	12
29	Effect of surface finishing on signal transmission loss of microstrip copper lines for high-speed PCB. Journal of Materials Science: Materials in Electronics, 2019, 30, 16226-16233.	2.2	11
30	Characterization and application of aggregated porous copper oxide flakes for cupric source of copper electrodeposition. Materials Letters, 2015, 139, 458-461.	2.6	10
31	Hydroquinone oriented growth control to achieve high-quality copper coating at high rate for electronics interconnection. Journal of the Taiwan Institute of Chemical Engineers, 2020, 112, 130-136.	5.3	10
32	Preparation and thermal effects of polyarylene ether nitrile aluminium nitride composites. Polymer International, 2014, 63, 546-551.	3.1	9
33	Numerical simulation and experiments to improve throwing power for practical PCB through-holes plating. Circuit World, 2019, 45, 221-230.	0.9	9
34	Surface coarsening of carbon fiber/cyanate ester composite for adhesion improvement of electroless copper plating as conductive patterns. Materials Chemistry and Physics, 2020, 255, 123597.	4.0	9
35	Cyanide-free silver immersion deposition involving 3-mercapto-1-propanesulfonic acid for copper finishing. Materials Chemistry and Physics, 2020, 244, 122671.	4.0	9
36	Preparation of rimose NiZnP electrode for hydrogen evolution reaction in alkaline medium by electroless and H 2 SO 4 etching. Journal of Alloys and Compounds, 2017, 719, 376-382.	5.5	8

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37	PET Surface Modification with Inkjet-Printing Pd²⁺/Epoxy Resin Solution for Selective Electroless Copper Plating. ACS Applied Electronic Materials, 2022, 4, 149-157.	4.3	7
38	Direct additive copper plating on polyimide surface with silver ammonia via plasma modification. Applied Surface Science, 2022, 587, 152848.	6.1	7
39	Copper coin-embedded printed circuit board for heat dissipation: manufacture, thermal simulation and reliability. Circuit World, 2015, 41, 55-60.	0.9	6
40	In-situ chemical polymerization of Cu-Polythiophenes composite film as seed layer for direct electroplating on insulating substrate. Electrochimica Acta, 2020, 330, 135358.	5.2	6
41	A novel structured spiral planar embedded inductor: Electroless-plating NiCoP alloy on copper coil as magnetic core. Journal of Magnetism and Magnetic Materials, 2019, 489, 165363.	2.3	5
42	Process, fundamental and application of one-step molten-salt synthezed BaTi2O5 nanorods. Journal of Alloys and Compounds, 2020, 826, 154064.	5.5	5
43	Effect of 3-mercapto-1-propane sulfonate sulfonic acid and polyvinylpyrrolidone on the growth of cobalt pillar by electrodeposition. Nanotechnology Reviews, 2022, 11, 1209-1218.	5.8	5
44	Communicationâ€"Localized Accelerator Pre-Adsorption to Speed Up Copper Electroplating Microvia Filling. Journal of the Electrochemical Society, 2019, 166, D467-D469.	2.9	3
45	Polymer-based Cu/Ag composite as seed layer on insulating substrate for copper addition of multi-dimensional conductive patterns. Journal of the Taiwan Institute of Chemical Engineers, 2021, 123, 254-260.	5.3	3
46	Investigation on Cuâ€“Sn intermetallic compounds growth and signal transmission loss of the diverse copper lines after soldering in printed circuit board. Journal of Materials Science: Materials in Electronics, 2021, 32, 22372-22386.	2.2	3
47	Anisotropic growth of electroless nickelâ€‘phosphorus plating on fine sliver lines for L-shape terminal electrode structure of chip inductor. Applied Surface Science, 2019, 496, 143633.	6.1	2
48	Additive-assisted cobalt electrodeposition as surface magnetic coating to enhance the inductance of spiral copper inductors. Surfaces and Interfaces, 2022, 28, 101603.	3.0	2
49	A Catalytic and Interfacing PEDOT:PSS/CuPc Polymerized on Cloth Fiber to Electroâ€Metalize Stretchable Copper Conductive Pattern. Advanced Materials Interfaces, 0, , 2101462.	3.7	2
50	A modified model of conductor roughness for manufacturing copper lines of printedcircuit board. Circuit World, 2021, ahead-of-print, .	0.9	1
51	Enhancing peel strength between liquid crystal polymer and copper with plasma treatment, surface oxidation, and silane coating. Journal of Applied Polymer Science, 2022, 139, .	2.6	1
52	Preparation and Properties of Cyanate/Epoxy-based Composite with Thermal Conductive Silica Particles. IOP Conference Series: Materials Science and Engineering, 2018, 422, 012003.	0.6	0